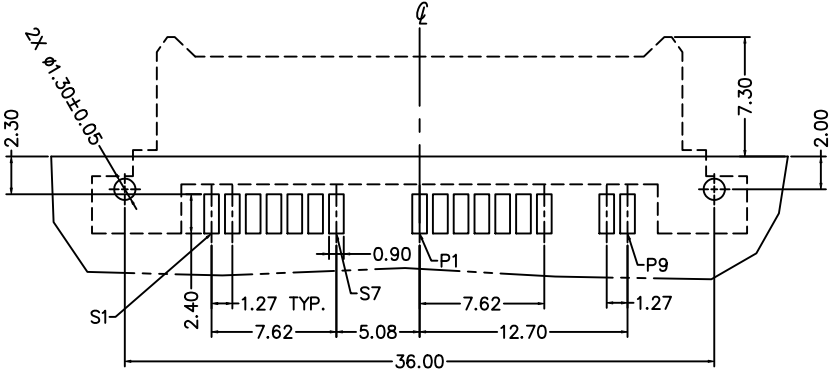
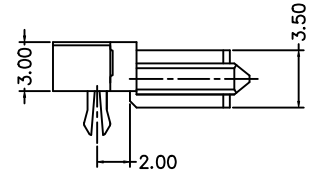
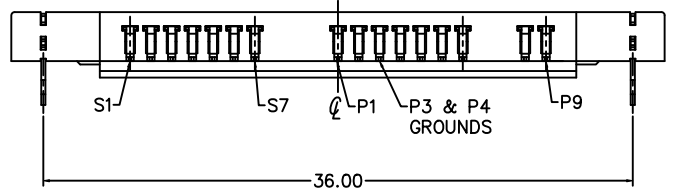
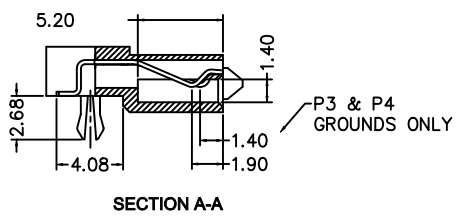
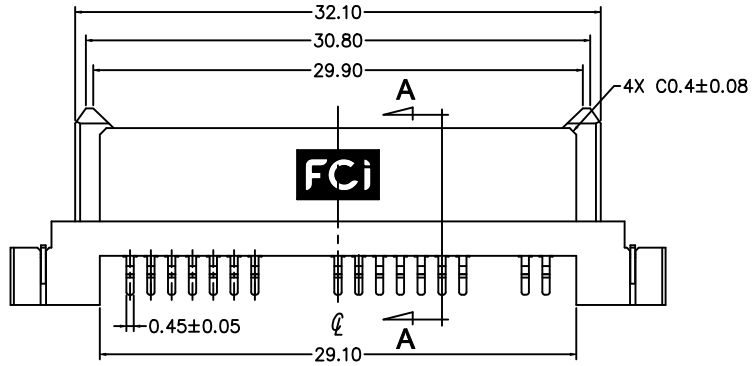
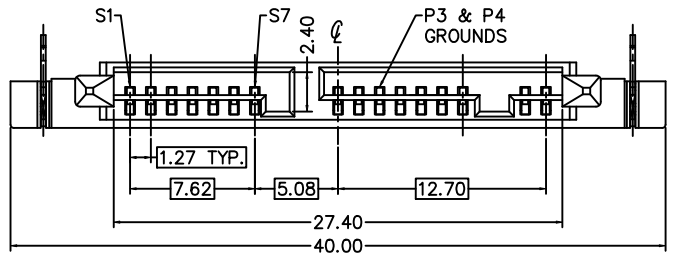


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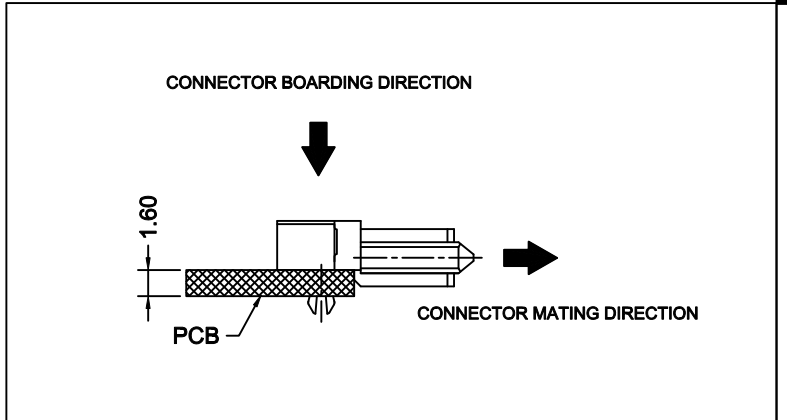


RECOMMENDED PCB LAYOUT
PCB THICKNESS : 1.6mm

NOTES:

1. MATERIAL
 - 1) HOUSING : HIGH TEMP THERMOPLASTIC UL94V-0(COLOR: BLACK)
 - 2) TERMINAL : COPPER ALLOY
 - 3) HOLD DOWN : COPPER ALLOY
2. FINISH
 - 1) TERMINAL : Au PLATING (CONTACT POINT) OVER 50u" NICKEL
 - 2) SOLDER TAIL : 50u" min MATT TIN OVER 50u" NICKEL
 - 3) HOLD DOWN : 50u" min MATT TIN OVER 50u" NICKEL
3. THE HOUSING WILL WITHSTAND EXPLOSURE TO 260° FOR 10 SEC. IN REFLOW SOLDER APPLICATION WITH 1.6MM MINIMUM CIRCUIT BOARD.
4. PRODUCT SPEC:GS-12-494
PACKING SPEC:GS-14-1283
5. PRODUCT NUMBERING:
10105229 - X 0 0 X LF

1: TRAY PACKING
0: 5U" GOLD PLATING



mat'l. code				tolerances unless otherwise specified			CUSTOMER COPY		FCI www.fciconnect.com	
ltr	ecn no	dr	date	linear	.X ± 0.38	projection	title			
A	T09-1141	S.LIN	11/02/09'	angles	.XX ± 0.25		MICRO S-ATA RECEP R/A, SMT TYPE			
					.XXX ± 0.15	MM	product family	SATA		code
				dr	STERLING LIN 11/02/09'	scale	size	dwg no		TWN
				enrg	STERLING LIN 11/02/09'	NA	A4	10105229		sheet
				chr	GARY HSIEH 11/02/09'					1 of 1
				appd	JOSEPH HSIA 11/02/09'					
sheet index	revision sheet	A	1					cage code		